

Thin film soldered RSAM on 7mm x 7mm W/Cu submount RSAM- λ -7t

SAM chip area	standard:	4mm x 4mm
Chip thickness	standard:	400 μ m
Front side	the RSAM is protected with a dielectric front layer	

The SAM chip is thin film soldered on a gold plated W/Cu submount using a Au/Sn solder.

Submount dimensions: 7mm x 7mm x 1mm

Submount material: W/Cu 90 / 10

The thin film soldering ensures a good thermal contact of the SAM to the submount

RSAM on W/Cu submount

